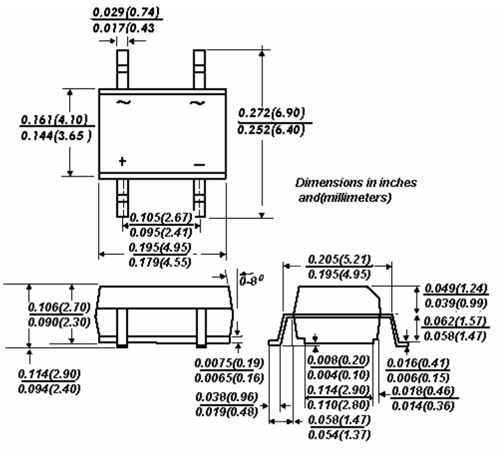
SMD SHANGSI

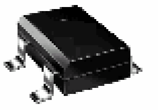
表面贴装整流桥 MB2S thru MB6S

Miniature Glass Passivated Single-Phase Surface Mount Bridge Rectifier
Reverse Voltage 200to 600V Forward Current 0.5A

FEATURES



- 表面贴装应用
- 塑料封装（MBS）
- 玻璃钝化芯片
- 高浪涌电流 35A
- 最高焊接温度 250℃ /10 秒



MECHANICAL DATA

- 封装：塑料封装:
- 焊接端子: 铅锡合金镀层
- 包装: 25K/箱 2.5K / Reel（13”）
- 重量: 0.22g

MAXIMUM RATINGS AND THERMAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.

	SYMBOLS	MB2S	MB4S	MB6S	UNITS
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	200	400	600	Volts
Maximum RMS Voltage	V_{RMS}	140	280	420	Volts
Maximum DC Blocking Voltage	V_{DC}	200	400	600	Volts
Maximum Average Forward output rectified current(see Fig :1) on glass-epoxy P.C.B. on aluminum substrate	$I_{F(AV)}$	0.5 0.8			Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	35.0			Amps
Maximum Instantaneous Forward Voltage drop per leg at 0.4A	V_F	1.0			Volts
Maximum DC Reverse Current T_A=25℃ at Rated DC Blocking Voltage T_A=125℃	I_R	5.0 100.0			μA
Rating for fusing (t<8.3ms)	I^2t	5.0			A^2sec
Typical Junction Capacitance per leg at 4.0V.1MHz	C_J	13.0			pF
Typical thermal resistance per leg	$R_{\Theta JL}$ $R_{\Theta JA}$ $R_{\Theta JA}$	20.0 85.0(1) 70.0(2)			℃/W
Operating junction and Storage Temperature Range	$T_J T_{STG}$	-55 to+150			℃

NOTES:

1. On glass epoxy P.C.B.mounted on0.05*0.05”(1.3*1.3mm)pads

2. On aluminum substrate P.C.B. with an area of 0.8”(20*20mm) mounted

3. On 0.05*0.05”(1.3*1.3mm) solder pad